

# Cool. Reliable. Hardware-Free.

## Power Site™

Automated Power  
Semiconductor Attachment  
Patented

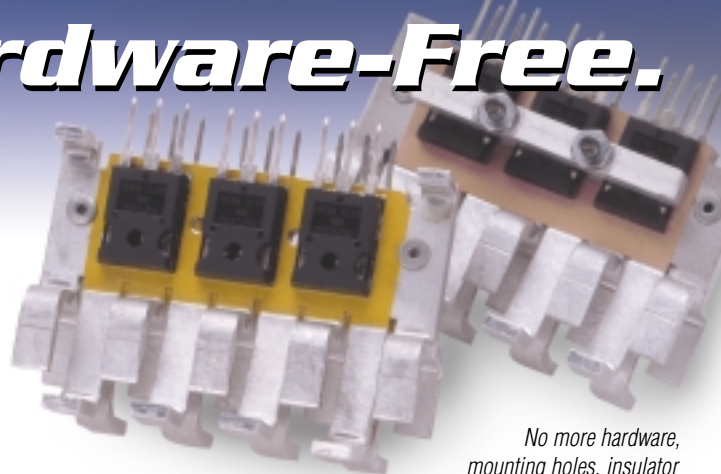
**Goodbye, hardware. Hello, cooler power devices.**

Chomerics introduces the latest advance in thermal interface technology. Our *PowerSite* process creates low thermal impedance, electrically isolated interface locations and solders power packages directly onto heat sinks.

The automated *PowerSite* process selectively bonds copper patches to aluminum heat sinks *only where power devices are to be mounted.*

No etching processes are required, allowing *PowerSite* patches to be applied to heat sinks of virtually any size or shape. As a final step, the process solders devices in place.

**Call now for *PowerSite* literature and samples.**



*No more hardware,  
mounting holes, insulator  
pads or pressure dependency*

- Thermal impedance as low as  $0.1^{\circ}\text{C}\text{-in}^2/\text{W}$
- High-temperature, all-polyimide insulation with thermally conductive Kapton\*MT for  $>4000$  volts dielectric strength
- Accommodates standard solderable packages — TO-220, TO-247, TO-218, etc.
- Design flexibility — reduce power device temperatures or heat sink size, or increase ambient temperature or power rating
- Automated *PowerSite* equipment consistently bonds patches and solders power devices in place.

### CHOMERICS

Chomerics Division, Parker Hannifin Corp.  
Woburn, Massachusetts, USA  
Tel 781-935-4850 • Fax 781-933-4318  
[www.aboutpowersite.com](http://www.aboutpowersite.com)

